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**PATENT ABSTRACTS OF JAPAN**

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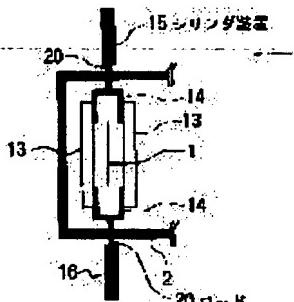
**(54) ELECTROPLATING DEVICE AND ELECTROPLATING METHOD**

(57)Abstract:

**PROBLEM TO BE SOLVED:** To prevent the generation of the difference in the coating weight in the surface and back faces and in the sheet width direction of a steel strip by shielding the tip parts of insoluble anodes wider than the sheet width of the steel strip by movable current shielding bodies and narrowing the conducting width than the sheet width.

**SOLUTION:** On both sides of a steel strip 1 continuously passed through the inside of a plating cell 2, insoluble anodes 13 wider than the sheet width of a steel strip 1 are oppositely arranged so as to sandwich the steel strip 1, and furthermore, current shielding bodies 14 movable in the sheet width direction are arranged via a cylinder device 15 to shield the tip parts of the insoluble anodes 13. In this plating device, in the case electric current is applied to the steel strip 1 and the insoluble anodes 13 and electroplating is executed, the above current shielding bodies 14 are moved to previously decided positions. As for this

positions, for example, the moving positions of the current shielding bodies and the distribution of the coating weight to the steel strip are previously found, and the positions of the current shielding bodies corresponding to the desired distribution of the coating weight are decided.



Detailed Descriptions of the Invention:

[0032]

As described above, according to the present invention, the current shielding bodies 14 movable in the sheet width direction of the steel strip 1 is provided so as to shield the tip parts of the insoluble anodes 13 and to be able to narrow the conducting width of the above described insoluble anodes 13, and electroplating which achieves a desired coating weight distribution can be applied by moving the current shielding bodies 14 to previously decided positions. More concretely, the relation of the plating coating weight distribution to the steel strip 1 and the conducting width of the insoluble anodes 13 corresponding to the positions of the current shielding bodies 14 is previously found, and with the position corresponding to the desired plating coating weight distribution to the steel strip 1 as the above described previously decides position, and the positional adjustment of the current shielding bodies 14 is performed, whereby the conducting width of the insoluble anodes 13 is adjusted, and electroplating with the desired coating weight distribution can be applied.